Symposium Agenda / Tuesday, May 6

7:45 am – 8:45 am	**Registration and Breakfast**
8:45 am – 9:00 am	**Welcome and Keynote Introduction**
SESSION ONE	**POLYMERS AND PROCESSING FOR SEMICONDUCTOR APPLICATIONS**
9:00 am – 9:45 am	**Keynote: Material Challenges in Mobile Device Packaging** Dr. Steve Bezuk, Qualcomm Inc.
9:45 am – 10:15 am	**Key Market Growth Areas in Polymers for IC Packaging** E. Jan Vardaman, TechSearch International, Inc.
10:15 am – 10:45 am	**Break & Exhibits**
10:45 am – 11:15 am	**Via Formation in Thin Film Polymers: Photo-Processing vs. Laser Ablation** Dr. Michael Töpper, Fraunhofer IZM
11:15 am – 11:45 am	**High Performance Temporary Bonding and De-Bonding Technology for Advanced Wafer Level Packaging Applications** Kai Zoschke, Fraunhofer IZM
11:45 am – 12:15 pm	**Analysis of Stress Buffer Effect of Organic Passivation Layer for Board Level Reliability Test** Mitsuru Fujita, Asahi Kasei E-Materials Corporation
12:15 pm – 1:45 pm	**Lunch & Exhibits**
1:45 pm – 2:15 pm	**Spin-on-Dielectric Passivation Materials Decisions for 3-D Devices** Brian Erwin, IBM Corporation
2:15 pm – 2:45 pm	**High-Temperature Resistant Polymide Gate Insulators for Solution-Processed Metal Oxide Thin-Film Transistors** Dr. Kwang-Suk Jang, Korea Research Institute of Chemical Technology
2:45 pm – 3:15 pm	**Thermodynamic Stability of Multilevel Microelectronic Structures: Polyimides on Ceramic** Dr. Robert Lacombe, Chairman, Materials Science and Technology Symposia
3:15 pm – 3:45 pm	**Break & Exhibits**
3:45 pm – 4:15 pm	**Improvement in Adhesion Strength of Positive-Tone Photo-Definable PBO Materials** Yuki Nakamura, Hitachi Chemical DuPont Microsystems Ltd.
4:15 pm – 5:00 pm	**Keynote: Investing in the Bleeding Edge of Technology (Without Getting Burned)** Jim Lee, Strategic Foresight Investments LLC
5:30 pm – 6:30 pm	**Reception in Museum**

Symposium Agenda / Wednesday, May 7

8:00 am – 8:45 am	**Breakfast**
8:45 am – 9:00 am	**Welcome and Keynote Introduction**
SESSION TWO	**POLYMERS IN PACKAGING**
9:00 am – 9:45 am	**Keynote: Polymer Innovations for Advanced Packaging Applications** John Hunt, ASE (US) Inc.
9:45 am – 10:15 am	**Thick Film Resist Sidewall Slope and Profile Control for RDL, Electro Plating and 3D Applications** Medhat Touky, AZ Electronic Materials USA Corporation
10:15 am – 10:45 am	**Development of Thicker Negative Tone Resist for Bumping Applications** Akito Hiro, JSR Corporation Japan
10:45 am – 11:15 am	**Break & Exhibits**
11:15 am – 11:45 am	**A 50µm, Single Layer, Self-Leveling Uniform Coat Process with Near Zero Waste Using AZ4620** Gary Hillman, S-Cubed Inc.
11:45 am – 12:15 pm	**Improved Plating Resists for Cu RDL and 3D Bumping Applications** Rosemary Bell, Dow Electronic Materials
12:15 pm – 1:45 pm	**Lunch & Exhibits**
1:45 pm – 2:15 pm	**Via Fabrication Using and Inkjettable, SU-8 Based Epoxy Resist** Adam Giang, MicroChem Corporation
2:15 pm – 2:45 pm	**Low Temperature Curable Positive-Tone Photodefinable Polymide** Dr. Daisaku Matsukawa, Tsukuba Research Laboratory, Hitachi Chemical Co., Ltd.
2:45 pm – 3:15 pm	**Break & Exhibits**
3:15 pm – 3:45 pm	**Properties and Characteristics of HD4100 PSPI Cured at 250˚C Microwaves** Bob Hubbard, Lambda Technologies
3:45 pm – 4:45 pm	**Panel: Material Requirements for Large Panel Processing** Moderated by E. Jan Vardaman Panelists: John Hunt, Dr. Mark Poliks, Dr. Elsa Reichmanis, Dr. Michael Töpper
5:30 pm – 7:00 pm	**Reception at Reflecting Pool**

Symposium Agenda / Thursday, May 8

7:30 am – 8:15 am	**Breakfast**
8:15 am – 8:30 am	**Welcome and Keynote Introduction**
SESSION THREE	**EMERGING APPLICATIONS AND POLYMER MATERIALS**
8:30 am – 9:15 am	**Keynote: Roll-to-Roll Manufacturing of Electronics – From Silicon Wafers to Flexible Plastic** Dr. Mark Poliks, State University of NY, Binghamton
9:15 am – 9:45 am	**Flexible Polymeric Devices: Molecular Ordering, Charge Transport and Macroscale Mobility** Dr. Elsa Reichmanis, Georgia Tech
9:45 am – 10:15 am	**High Temperature, Transparent, Low Birefringence Resin Systems for Flexible Device Substrates** Dr. Matt Graham, Akron Polymer Systems, Inc.
10:15 am – 10:45 am	**Break & Exhibits**
10:45 am – 11:15 am	**Aqueous-Base Developable Photoimageable Dielectric Materials for Optical Applications** Eric Huenger, Dow Electronic Materials
11:15 am – 11:45 am	**Highly Integrated Surface Ligand Platform for Polymer Nanocomposites and Their Applications in Advanced LED Lighting Systems** Ying Li, Rensselaer Polytechnic Institute
11:45 am – 12:15 pm	**Controlling Thermal Impedance Using Surface Engineering** Joel Plawsky, Rensselaer Polytechnic Institute